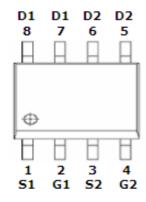


DESCRIPTION

STP4953 is the dual P-Channel logic enhancement mode power field effect transistor which is produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as LCD backlight, notebook computer power management, and other battery powered circuits.

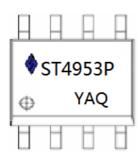
PIN CONFIGURATION SOP-8



FEATURE

- -30V/-5.2A, $R_{DS(ON)} = 60m\Omega$ @VGS =-10V
- -30V/-4.5A, $R_{DS(ON)} = 80 \text{m}\Omega$ $@V_{GS} = -6.0V$
- -30V/-3.8A, $R_{DS(ON)} = 90m\Omega$ @V_{GS} = -4.5V
- Super high density cell design for extremely low R_{DS(ON)}
- Exceptional on-resistance and maximum DC current capability
- SOP-8 package design

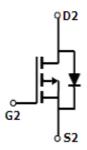
PART MARKING SOP-8



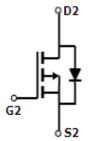
Y: Year Code

A: Week Code

Q: Prucess Code



P-Channel



P-Channel



ABSOULTE MAXIMUM RATINGS (Ta = 25° C Unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		V _{DSS}	-30	V
Gate-Source Voltage		V _{GSS}	±20	V
Continuous Drain Current (TJ=150 $^{\circ}$ C)	Ta=25°C Ta=70°C	ΙD	-5.2 -4.2	А
Pulsed Drain Current		I _{DM}	-30	Α
Continuous Source Current (Diode Conduction)		Is	-2.3	А
Power Dissipation	Ta=25°C Ta=70°C	PD	2.7 1.8	W
Operation Junction Temperature		Тэ	-55/150	$^{\circ}$
Storgae Temperature Range		Tstg	-55/150	$^{\circ}\mathbb{C}$
Thermal Resistance-Junction to Ambient		$R_{ heta}$ ja	70	°C/W



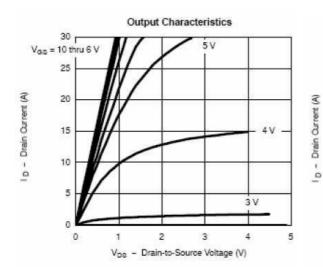
ELECTRICAL CHARACTERISTICS ($Ta = 25^{\circ}C$ Unless otherwise noted)

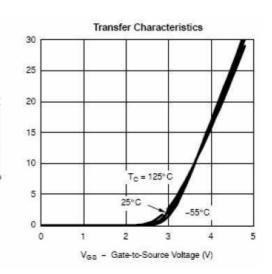
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V,I _D =-250uA	-30			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=-250$ uA	-1.0		-3.0	V
Gate Leakage Current	Igss	V _{DS} =0V,V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain	IDSS TJ=55℃	V _{DS} =-30V,V _{GS} =0V			-1	
Current		V _{DS} =-30V,V _{GS} =0V			-5	uA
On-State Drain Current	ID(on)	V _{DS=-} 5V,V _{GS} =10V	-25			Α
Drain-source On-Resistance	RDS(on)	V _G S=-10V, I _D =-5.2A V _G S=-6.0V, I _D =-4.5A V _G S=-4.5V,I _D =-4.0A		0.50 0.60 0.75	0.60 0.80 0.90	Ω
Forward Tran Conductance	gfs	V _{DS} =-10V,I _D =-5.0A		9.0		S
Diode Forward Voltage	V _{SD}	Is=-2.0A,V _{GS} =0V		-0.8	-1.2	V
Dynamic						
Total Gate Charge	Qg			15	10	
Gate-Source Charge	Qgs	V_{DS} =-15V, V_{GS} =-10V I_{D} =-5.0A		4.0		nC
Gate-Drain Charge	Qgd	15 3.67.		2.0		
Input Capacitance	Ciss			680		
Output Capacitance	Coss	$V_{DS} = -15V, VGS = 0V$ $f = 1MHz$		120		pF
Reverse TransferCapacitance	Crss	. 11112		75		
Turn-On Time	td(on) tr			7.0	15	nS
		V_{DD} =15 V , R_{L} =15 Ω I_{D} =-1.0 A , V_{GEN} =-10 V		10	20	
Turn-Off Time	td(off) tf	$R_{G}=6\Omega$		40	80	
Turn on time				20	40	

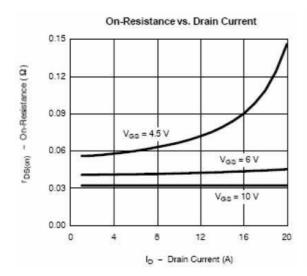


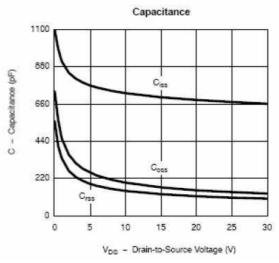


TYPICAL CHARACTERICTICS (25°C Unless Note)



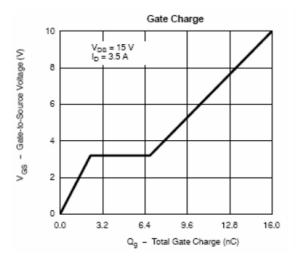


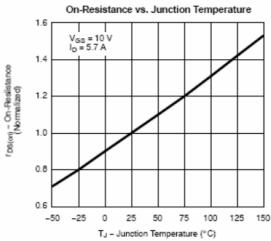


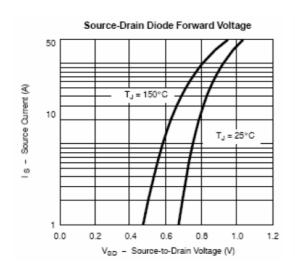


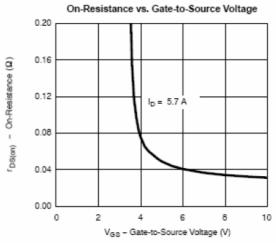


TYPICAL CHARACTERICTICS (25°C Unless Note)



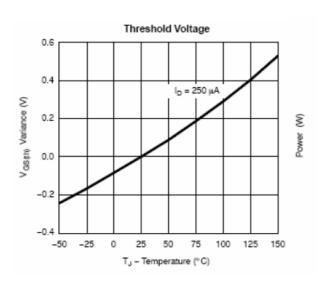


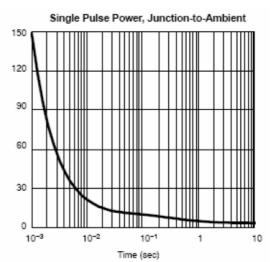


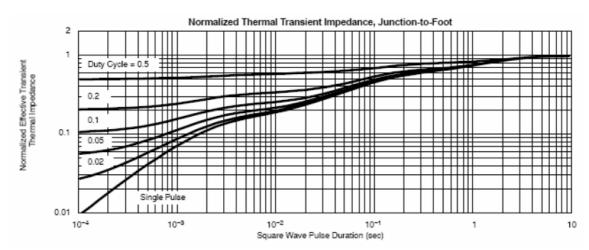




TYPICAL CHARACTERICTICS (25°C Unless Note)

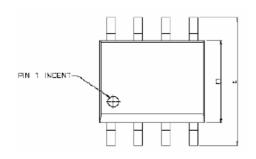


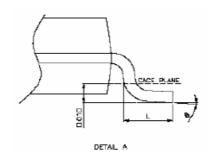


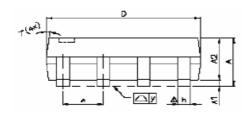


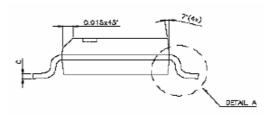


SOP-8 PACKAGE OUTLINE









	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
SYMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
A	1.47	1.60	1.73	0.058	0.063	0.068
A1	0.10	-	0.25	0.004		0.010
A2	-	1.45	_		0.057	
b	0.33	0.41	0.51	0.013	0.016	0.020
С	0.19	0.20	0.25	0.0075	0.008	0.0098
D	4.80	4.85	4.95	0.189	0.191	0.195
Ε	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
e		1.27			0.050	
L	0.38	0.71	1.27	0.015	0.028	0.050
<u>^</u> y			0.076	-	. :	0.003
0	0.	_	8,	0,	s	8*